

Method Statement Sika[®] AcouBond-System and Cordon / Beaded Application

Corporate Construction

Scope:

Description of the Sika[®] AcouBond-System
and the cordon-wise / beaded application.



The information contained herein and any other advice are given in good faith based on Sika's current knowledge and experience of the products when properly stored, handled and applied under normal conditions in accordance with Sika's recommendations. The information only applies to the application(s) and product(s) expressly referred to herein. In case of changes in the parameters of the application, such as changes in substrates etc., or in case of a different application, consult Sika's Technical Service prior to using Sika products. The information contained herein does not relieve the user of the products from testing them for the intended application and purpose. All orders are accepted subject to our current terms of sale and delivery. Users must always refer to the most recent issue of the local Product Data Sheet for the product concerned, copies of which will be supplied on request.



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1. Substrate

1.1 Substrate quality

Clean and dry, homogeneous, even, free from oils and grease, dust and loose or friable particles. Paint, cement, laitance and other poorly adhering particles must be removed.



1.2 Substrate preparation

- **Concrete / cement screeds:**
Must be ground and thoroughly cleaned with an industrial vacuum cleaner.
- **Anhydrite screeds / Anhydrite floating screeds:**
Must be ground and thoroughly cleaned with an industrial vacuum cleaner shortly before bonding starts.



Full surface grinding.



Removing dust with an industrial vacuum.

- **Broadcast mastic asphalt:**
Must be primed with Sika Primer MB.
For instructions for use, see the current Product Data Sheet for Sika Primer MB.
- **Existing glazed ceramic tiles:**
Degrease and clean with Sika Cleaner-205 or grind the tile surfaces and vacuum thoroughly.
- **Wood- / gypsum boards (e.g. chipboard, plywood):**
Glue / screw the boards to the substructure. They must be fixed to the substrate.
For floating sub floors, please contact our Technical Service Department for advice and assistance.
- **Other substrates:**
Please contact our Technical Service Department for advice and assistance.
SikaBond adhesives can be used without priming on suitable cementitious floors, anhydrite floors, chipboard, concrete and ceramic tile surfaces. For broadcast mastic asphalt, cementitious floors with excessive moisture content and for use over old adhesive residues or on weak substrates use Sika Primer MB. For detailed instructions please refer to the current Product Data Sheet of Sika Primer MB or contact our Technical Service Department.

1.3 Substrate temperature

During laying and until SikaBond has fully cured the substrate and ambient temperatures should be $> +15^{\circ}\text{C}$ and with under floor heating $\sim +20^{\circ}\text{C}$.

1.4 Ambient temperature

Ambient temperatures should be between $+15^{\circ}\text{C}$ and $+35^{\circ}\text{C}$.

1.5 Substrate moisture content

Permissible substrate moisture content **without** under floor heating:

- 2.5% CM for cement screeds (ca. 4% Tramex / Gravimetric weight percent)
- 0.5% CM for anhydrite screeds

Permissible substrate moisture content for use **with** under floor heating:

- 1.8% CM for cement screeds (ca. 3% Tramex / Gravimetric weight percent)
- 0.3% CM for anhydrite screeds

1.6 Substrate strength

1.6.1 Shear strength

The Press-o-Mess device measures the surface strength of the screed. Two defined wood pieces are bonded in a given distance apart on the floor. After the adhesive is properly cured, the device is set between them. Whilst turning the handle, the device spreads apart and the pressure against the two wood pieces is shown on a gauge. For more information please consult the manufacturers operating manual.



- *Minimum shear strength:*
 - > 1.5 N/mm^2 for wood floor bonding (determined with rigid adhesive)
 - > 2.0 N/mm^2 for wood block paving (determined with rigid adhesive)



1.6.2 Pull off strength

Type of subfloor	Parquet	Wood paving
Cementitious	ZE 20 - 30	ZE 30
Anhydrite	AE 20 - 30	AE 30



- *Minimum pull off strength:*
 - > 1.0 N/mm² for wood floor bonding (determined with rigid adhesive)
 - > 1.2 N/mm² for wood block paving (determined with rigid adhesive)

Sika Primer MB is used to improve the surface strength. In case the substrate strength is inadequate then Sika Primer MB is used as substrate strengthener.

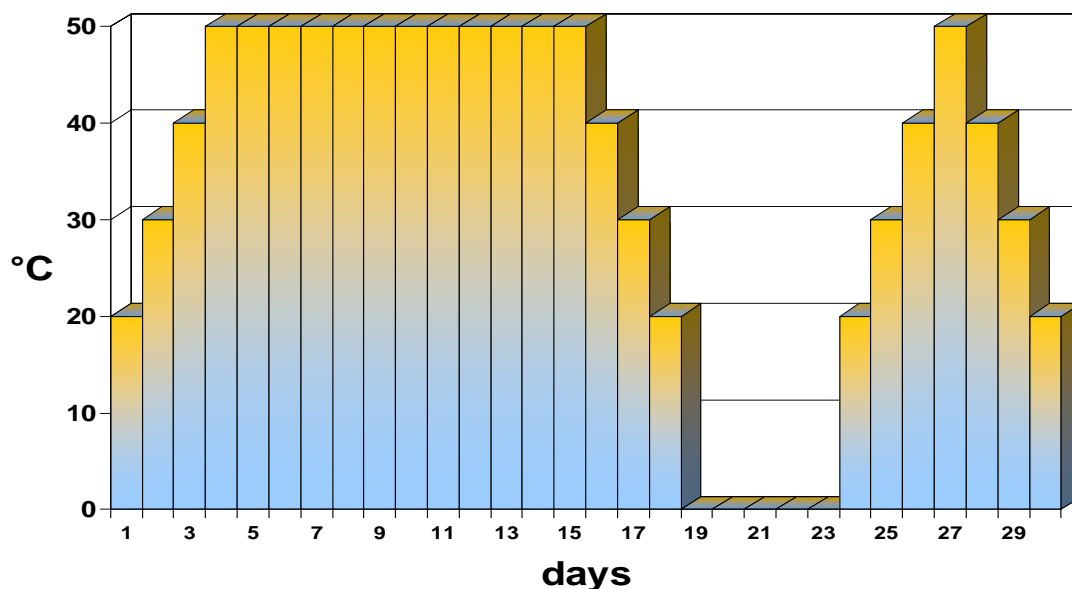
- *Minimum requirements for substrate if strengthened with SikaPrimer MB:*
0.8 N/mm² (pull off) or if not measurable > 8N/mm² compressive strength for Sika elastic wood floor adhesives

1.7 Under floor heating

DIN 18356 states: Before laying wood flooring systems on floors with underfloor heating, they must be preheated for a sufficiently long period to ensure adequate drying of the screed.

To avoid physical damage to the heating installation, moisture measurements should only be taken at predetermined measuring points. A preheating operation is usually carried out to test the efficiency and integrity of the heating system itself, but in most cases this is insufficient to reduce the screed moisture content to the required level. Further heating is therefore required to achieve a suitable moisture level and conditions for laying wood floors. This requirement should be included in the contract documents. Experience has shown that coordination of other trades and the wood floor contractors is of primary importance. Strict attention to their coordination and supervision will avoid damage due to excessive screed moisture.

A typical program for laying wood flooring is as follows:



The heating times shown should always be considered as minimum periods. Longer heating times provide extra security and are always desirable, particularly if the selected wood is liable to swell.

For more information about different substrates please consult the Sika Method Statement - 'Substrate Pre-Treatment for Wood Floor Bonding'.



2. Application Method for the Sika AcouBond System

Application:

After the correct substrate preparation, cut the SikaBond adhesive sausage end. Insert the sausage into gun and screw on triangular nozzle.



Laying SikaLayer:

Roll out SikaLayer parallel to the laying direction of the wood. The mat is placed against the wall with no or little distance.

In case of small wood pieces, place layer approx. 25mm from the wall. Here a bead (A) is applied in order to support the wood properly. Max distance from the last bead to the wall (B) (small side of mat) is 2 - 3cm.

If necessary cut layer mat.

For small wood pieces, place SikaLayer approx. 13 mm away from adjacent layer (C).



Application of Adhesive:

Apply the adhesive with a manual or pneumatic gun into all cut-outs. The nozzle must be held vertical to the substrate at a 90° right angle.



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Placing wood floor pieces:

Place the wood floor pieces within the appropriate laying time. Press the wood floor firmly into the adhesive until the wood lies tight on the layer mat. Adhesive consumption is between 500 - 600 ml/m² (1 Box / roll). Wood can be joined together, using a hammer and an impact block, rubber mallet or by hand. A perimeter gap of 10 - 15mm between the walls, columns etc. and the wood floor must be maintained



Using temporary fixing straps:

When using solid wood, Sika recommends the use of temporary fixing straps to keep joints tight, and weights, to hold the wood in place while the adhesive cures.



Cleaning:

Fresh, uncured adhesive remaining on the wood floor surface must be removed immediately with a clean cloth and if necessary cleaned with Sika Remover-208 or Sika TopClean-T. Note: Always test the wood floor surface for compatibility.

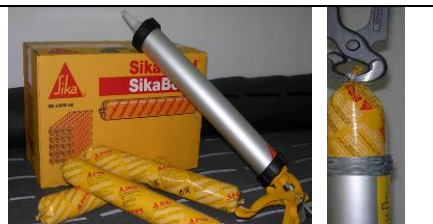


Prior to any use please consult the relevant current Product Data Sheets.

3. Application Method for Cordon / Beaded Application

Application:

After the correct substrate preparation, cut the SikaBond adhesive sausage end. Insert the sausage into gun and screw on triangular nozzle.

**Application of Adhesive:**

Apply the adhesive with a manual or pneumatic gun. Apply the adhesive beads approx. every 150 mm at right angles to the laying direction of the wood floor. The nozzle must be held vertical to the substrate - at a 90° right angle.

**Placing Wood floor pieces:**

Place the wood floor pieces within the appropriate laying time. Adhesive consumption is between 200 - 300 ml/m². Wood can be joined together, using a hammer and an impact block, rubber mallet or by hand.

**Using temporary fixing straps:**

When using solid wood, Sika recommends the use of temporary fixing straps to keep joints tight, and weights, to hold the wood in place while the adhesive cures.

**Cleaning:**

Fresh, uncured adhesive remaining on the wood floor surface must be removed immediately with a clean cloth and if necessary cleaned with Sika Remover-208 or SikaTopClean-T. Note: Always test the wood floor surface for compatibility.



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